

Title (en)  
Electroplating process and composition

Title (de)  
Verfahren und Zusammenstellung zur Elektroplattierung

Title (fr)  
Procédé et méthode d'électrodéposition

Publication  
**EP 0731192 B1 19990630 (EN)**

Application  
**EP 95103485 A 19950310**

Priority  
• EP 95103485 A 19950310  
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Abstract (en)  
[origin: EP0731192A1] A process for electroplating a nonconducting substrate comprising formation of a film of a conductive polymer on the surface of a nonconducting substrate and electrolytic deposition of metal thereover. The conductive film is formed by deposition of the conductive polymer onto said surface from an aqueous suspension of said polymer.

IPC 1-7  
**C25D 5/54**; **H05K 3/42**

IPC 8 full level  
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CPC (source: EP US)  
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